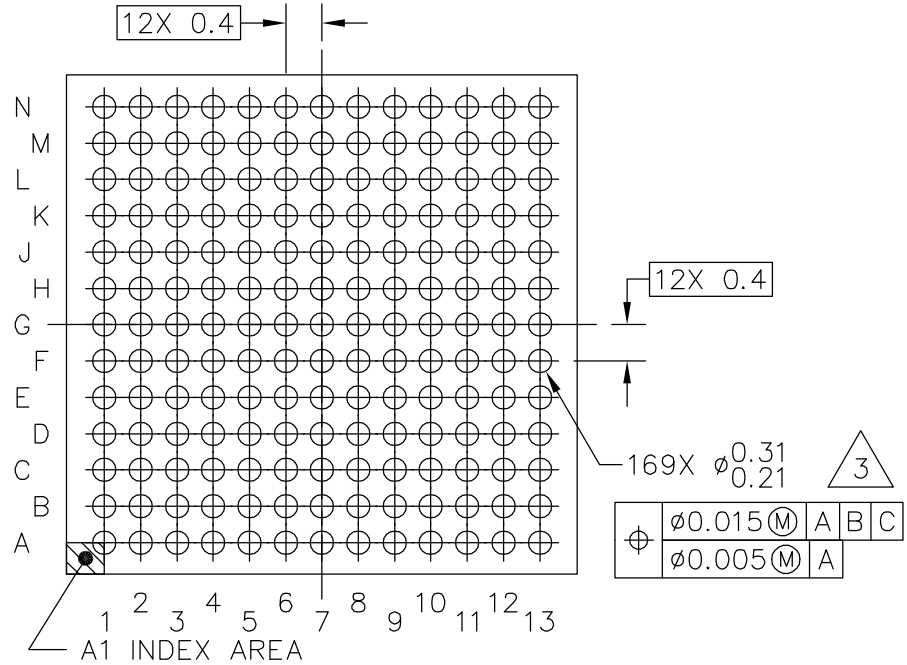
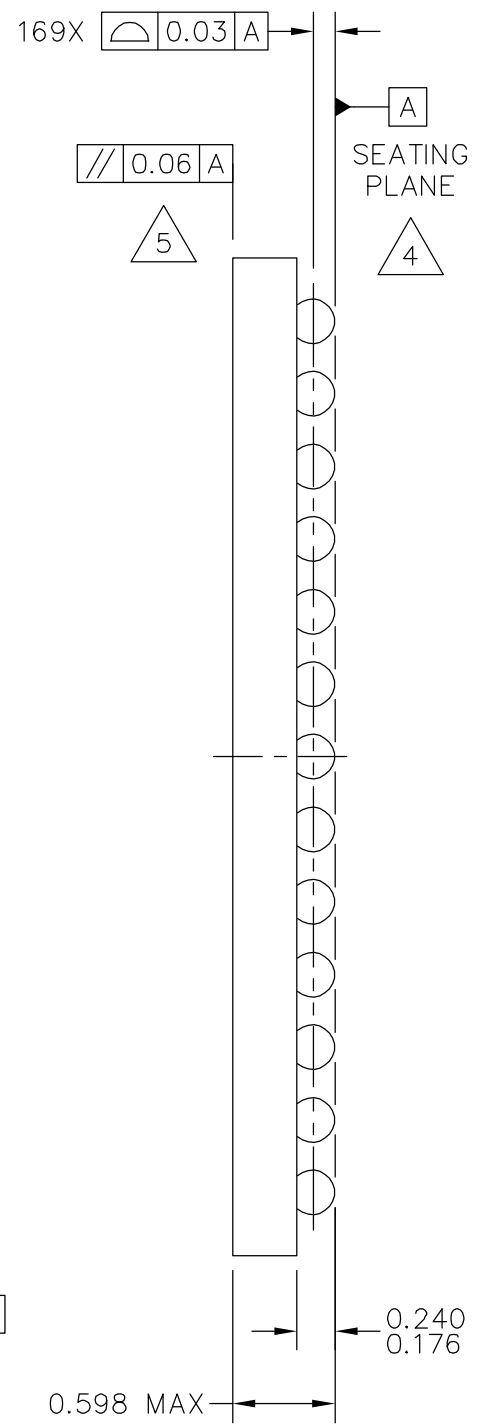


TOP VIEW



BOTTOM VIEW



VIEW D-D

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE
TITLE: WLCSP, 5.631 X 5.495 X 0.563 PKG, 0.4 MM PITCH, 169 I/O	DOCUMENT NO: 98ASA00640D	REV: A
	STANDARD: NON-JEDEC	
	SOT1777-1	27 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: WLCSP, 5.631 X 5.495 X 0.563 PKG, 0.4 MM PITCH, 169 I/O		DOCUMENT NO: 98ASA00640D	REV: A
		STANDARD: NON-JEDEC	
		SOT1777-1	27 JAN 2016